ECE-606 Homework No. 7 Assigned: Oct. 11 Due: Oct. 18

- 1) For an abrupt p^+n silicon diode, the doping concentration in the n-region is 10^{16} per cm³. The width of the n-region is 2 µm. Assuming this width is much smaller than the hole diffusion length, calculate the reverse saturation current at 300K and 400K. The area of the diode is 100 µm x 100 µm and the hole mobility is 350 cm²/V.s at both temperatures.
- 2) Solve SDF 6.10
- 3) A silicon p-n junction diode with area $A = 10 \ \mu m^2$, has doping $N_A = 10^{17} \ cm^3$ on the p-side and doping $N_D = 10^{16} \ cm^3$ on the n-side. Calculate the storage charge in the depletion region and the diffusion charge for an applied voltage equal to 1V (reverse-biased). Assume that the *p*-type region is much smaller than the diffusion length with $W_p = 500 \ nm$ but *n*-type region is long with hole diffusion length $L_p = 50 \ \mu m$.
- 4) Consider a one-dimensional p-n junction whose two conducting surfaces are metal layers at the two surfaces x = -T_p and x = T_n. The enclosed volume is the semiconductor slice between the two parallel planes located at x = -T_p and x = T_n. The space charge layer extend from x = -x_p to x = x_n. Using Gauss theorem, prove that the total space-charge enclosed within the space-charge layer is zero.
- 5) Compute the position of the Fermi energy relative to the intrinsic Fermi level on the p-side of a p-n junction diode. Assume $N_A = 10^{18}$ cm⁻³. Assume room temperature condition prevails.
- 6) Perform a search and outline the basic steps in the fabrication of a discrete planar p-n junction diode. You can use the information available on the web to aid your answer.
- 7) Compare the plots of forward current-voltage characteristics of Ge, Si, and GaAs p⁺n junction diode. Assume that the diodes have identical structures and doping concentration. Please give a short mathematical argument to support your I-V sketch.

You will not secure any credit for drawing the characteristics without a proof/reasoning.